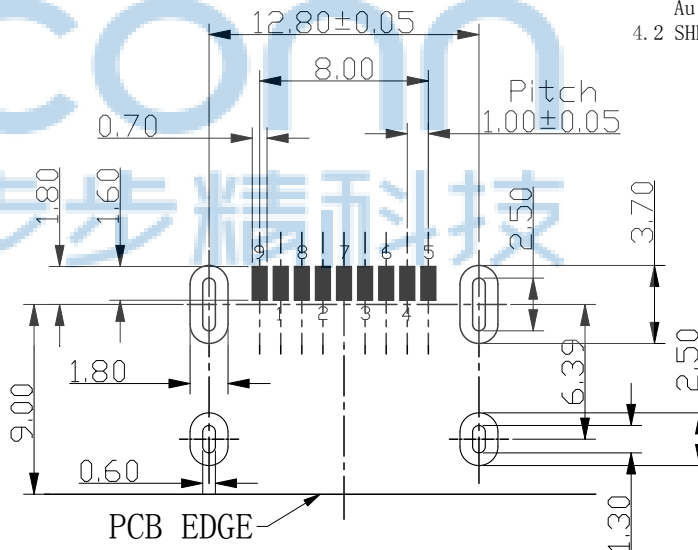
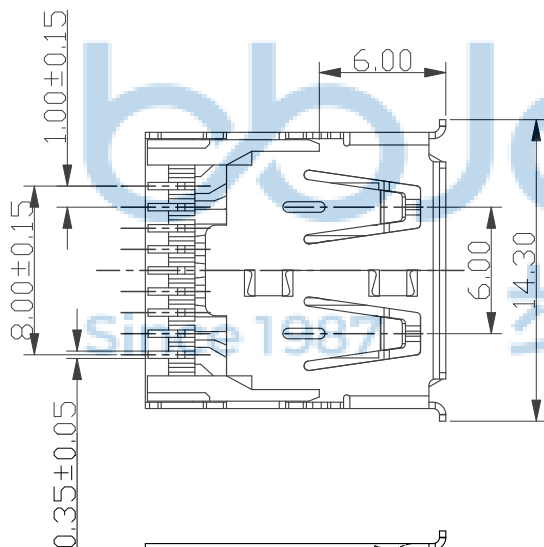
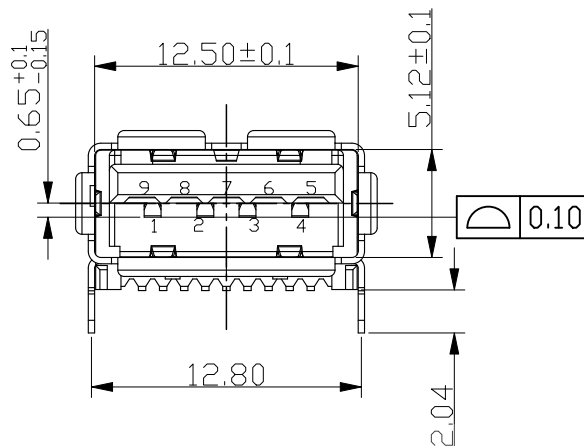
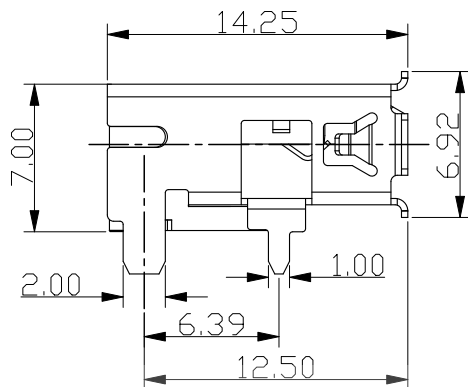
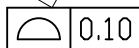
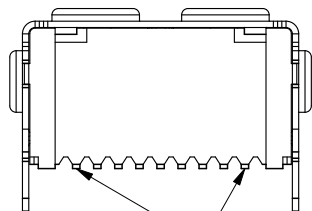




RECOMMENDED PCB LAYOUT
TOLERANCE: $\pm 0.05\text{mm}$

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: HIGH TEMPERATURE PLASTIC LCP
- 1.2 CONTACT: BRONZE
- 1.3 SHELL: BRASS

2. ELECTRICAL CHARACTERISTICS:

- 2.1 CONTACT RESISTANCE: $30\text{m}\Omega$ MAXIMUM
- 2.2 CONTACT CURRENT RATING: 1.5A
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE: 100 V AC R.M.S.
- 2.4 INSULATION RESISTANCE 100 MEGOHMS MIN
- 2.5 OPERATING TEMPERATURE: $-40^\circ\text{C} \sim 85^\circ\text{C}$

3. MECHANICAL CHARACTERISTICS:

- 3.1 MATING FORCE: 3.57kgf MAX
- 3.2 UNMATED FORCE: 0.82kgf MIN AFTER TEST
- 3.3 DURABILITY MANDATORY: 1500 CYCLES

4. PLATING

4.1 TERMINAL:

- 50u" MIN NICKEL ALL OVER
- 80u" MIN Tin ON SOLDER AREA
- Au G/F ON CONTACT AREA

4.2 SHELL: 50u" MIN. NICEL ALL OVER



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PDWG. NO: 0886-1



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.X: ± 0.38 X°: $\pm 3^\circ$
.XX: ± 0.25 X°: $\pm 2^\circ$
.XXX: ± 0.13 X°: $\pm 1^\circ$

APPD. JM_Zheng
CHKD. LYX
DR. TSP

NAME: USB 3.0 A母 90度 短体 SMT 四脚插
卷边 铜壳 LCP蓝胶 L=14.25 编带

PJ. NO.: 127-271-090008-K4G

SIZE: A4 DRW NO.:

FINISH: SEE NOTES

SCALE: N/A

MAT' L.: SEE NOTES

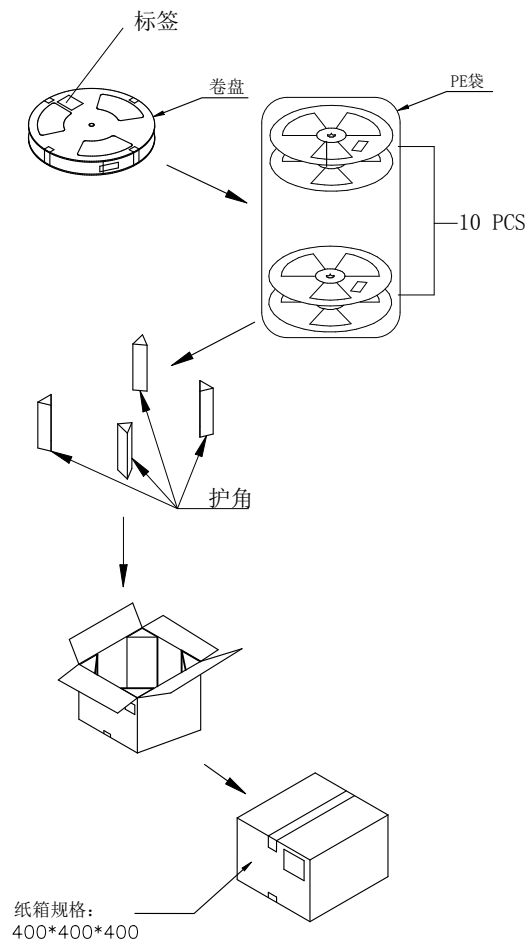
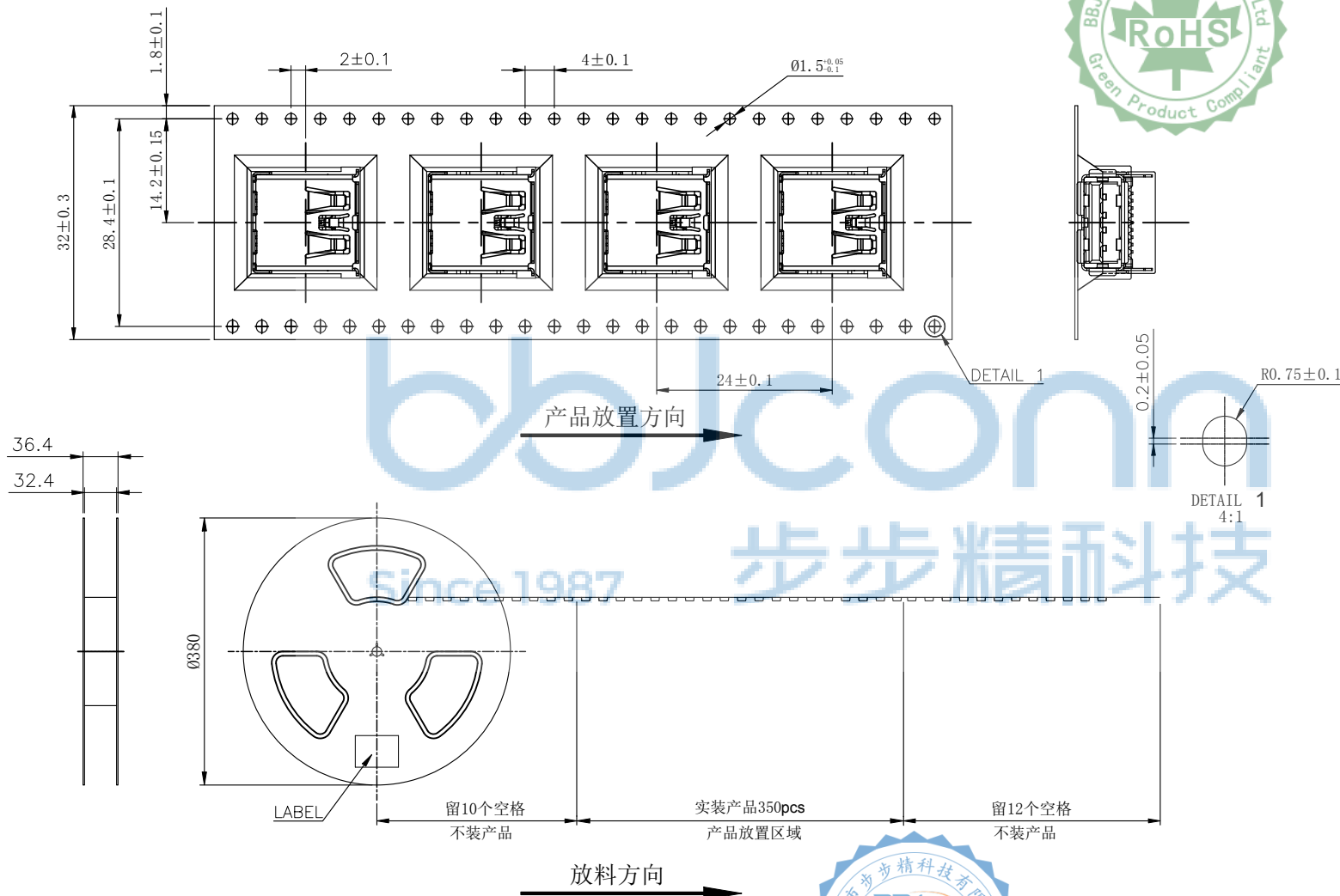
REV.: A0

UNIT: mm

PAGE: 1/2



REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



NOTE:

1. MATERIAL:

BOX: FIBREBOARD, CORRUGATED, DOUBLE WALL.

TAPE: POLYSTYRENES, HEAT-RESISTANT TEMPERATURE: 120°C, 透明 (Transparent) COLOR.

REEL: POLYSTYRENES, HEAT-RESISTANT TEMPERATURE: 70°C, BLUE COLOR.

BAG: POLYETHYLENE, HEAT-RESISTANT TEMPERATURE: 100°C.

2. PEELING STRENGTH: 0.1 ~ 1.3 N (10 ~ 130 GRAMS)

3. PEELING SPEED: 300 mm/min.

4. EACH BAG SHALL BE INCLUDED DESICCANT.



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DR. TSP

.X: ±0.38 .X°: ±3°
.XX: ±0.25 .X°: ±2°
.XXX: ±0.13 .XX°: ±1°

NAME: USB 3.0 A母 90度 短体 SMT 四脚插
卷边 铜壳 LCP蓝胶 L=14.25 编带

PJ. NO.: 127-271-090008-K4G
SIZE: A4 DRW NO.:
FINISH: SEE NOTES MAT'L.: SEE NOTES
SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2

350 10 3500 PCS -- KG -- KG
PCS/ REEL REELS/ CARTON QUANTITY GROSS WEIGHT NET WEIGHT

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